

CMOS 8-bit Single Chip Microcomputer

Description

The CXP842P24 is a CMOS 8-bit single chip microcomputer integrating on a single chip an A/D converter, serial interface, timer/counter, time base timer, capture timer/counter, and remote control reception circuit besides the basic configurations of 8-bit CPU, ROM, RAM, and I/O port.

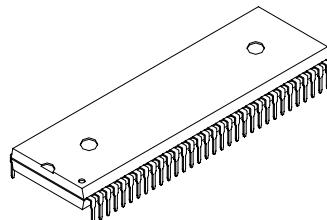
The CXP842P24 also provides a power-on reset function and a sleep/stop function that enables lower power consumption.

This IC is the PROM-incorporated version of the CXP84224 with built-in mask ROM. This provides the additional feature of being able to write directly into the program. Thus, it is most suitable for evaluation use during system development and for small-quantity production.

Features

- Wide-range instruction system (213 instructions) to cover various types of data
 - 16-bit arithmetic/multiplication and division/boolean bit operation instructions
- Minimum instruction cycle 400ns at 10MHz operation
- Incorporated PROM capacity 24K bytes
- Incorporated RAM capacity 624 bytes
- Peripheral functions
 - A/D converter 8 bits, 8 channels, successive approximation method
(Conversion time of 32 μ s/10MHz)
 - Serial interface Incorporated 8-bit, 8-stage FIFO
(Auto transfer for 1 to 8 bytes), 1 channel
 - Timer 8-bit timer
 8-bit timer/counter
 19-bit time base timer
 16-bit capture timer/counter
 - Remote control reception circuit 8-bit pulse measuring counter, 6-stage FIFO
 - PWM output 14 bits, 1 channel
- Interruption 14 factors, 14 vectors, multi-interruption possible
- Standby mode Sleep/stop
- Package 64-pin plastic SDIP

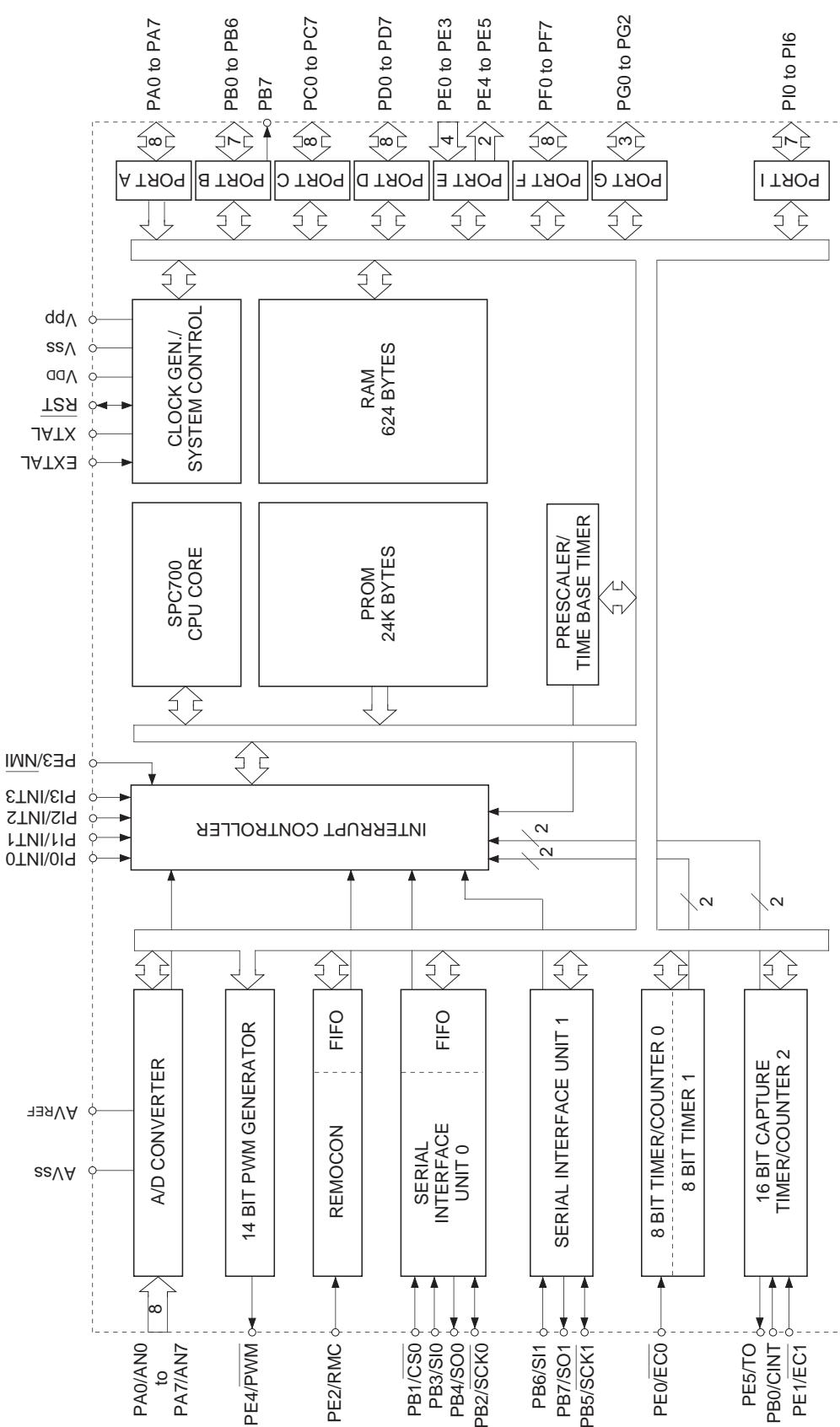
64 pin SDIP (Plastic)

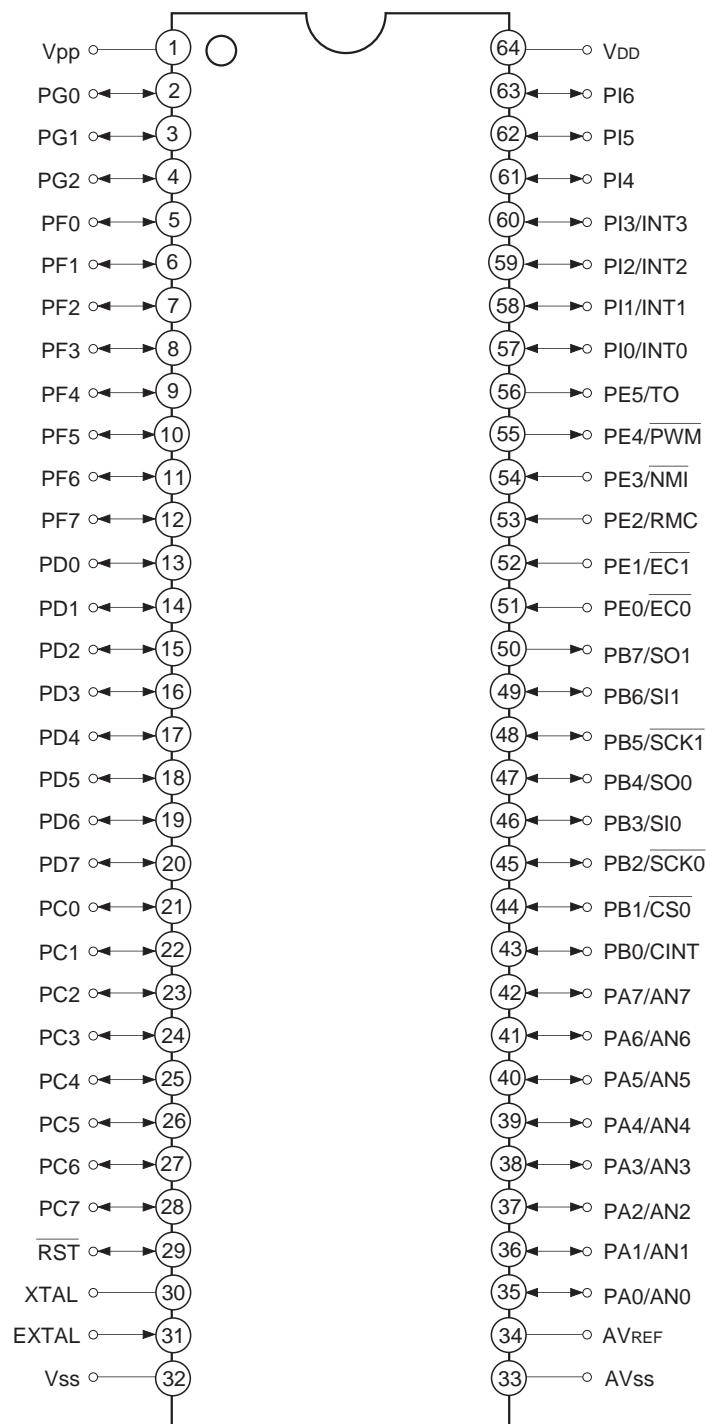


Structure

Silicon gate CMOS IC

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Block Diagram

Pin Assignment (Top View)

Note) Vpp (Pin 1) is always connected to VDD.

Pin Description

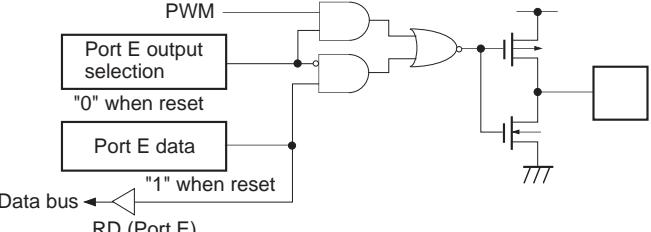
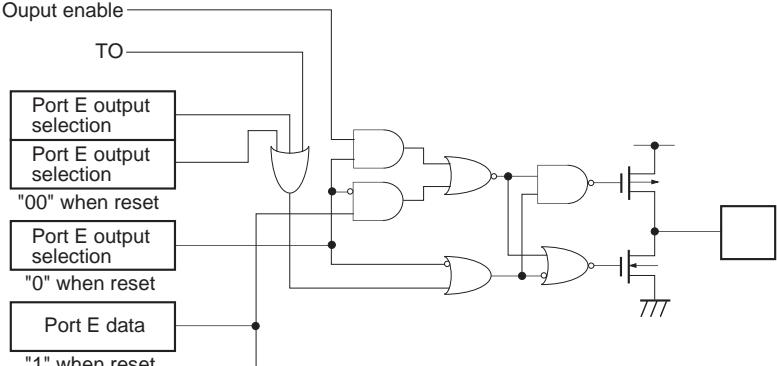
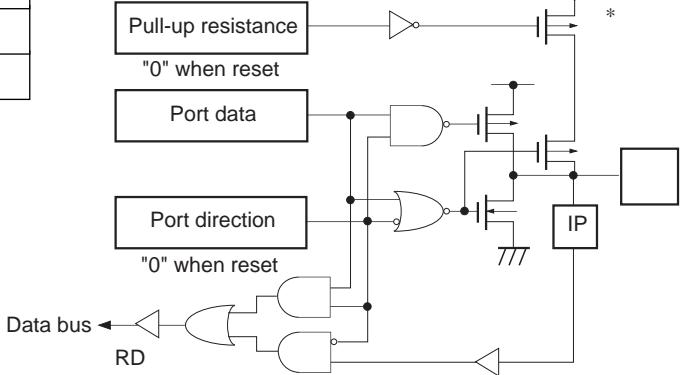
Symbol	I/O	Description	
PA0/AN0 to PA7/AN7	I/O/Analog input	(Port A) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of the pull-up resistance can be set through the software in a unit of 4 bits. (8 pins)	Analog inputs to A/D converter. (8 pins)
PB0/CINT	I/O/Input	(Port B)	External capture input to 16-bit timer/counter.
PB1/ <u>CS0</u>	I/O/Input		Chip select input for serial interface (CH0).
PB2/ <u>SCK0</u>	I/O/I/O		Serial clock I/O (CH0).
PB3/SI0	I/O/Input		Serial data input (CH0).
PB4/SO0	I/O/Output		Serial data output (CH0).
PB5/ <u>SCK1</u>	I/O/I/O		Serial clock I/O (CH1).
PB6/SI1	I/O/Input		Serial data input (CH1).
PB7/SO1	Output/Output	(8 pins)	Serial data output (CH1).
PC0 to PC7	I/O	(Port C) 8-bit I/O port. I/O can be set in a unit of single bits. Capable of driving 12mA sink current. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	
PD0 to PD7	I/O	(Port D) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	
PE0/ <u>EC0</u>	Input/Input	(Port E) 6-bit port. Lower 4 bits are for inputs; upper 2 bits are for outputs. Incorporation of pull-up resistor can be set through the software. (6 pins)	External event inputs for timer/counter. (2 pins)
PE1/ <u>EC1</u>	Input/Input		Remote control reception circuit input.
PE2/RMC	Input/Input		Non-maskable interruption request input.
PE3/ <u>NMI</u>	Input/Input		14-bit PWM output.
PE4/ <u>PWM</u>	Output/Output		Rectangular wave output for 16-bit timer/counter (duty output 50%).
PE5/TO	Output/Output		
PF0 to PF7	I/O	(Port F) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	

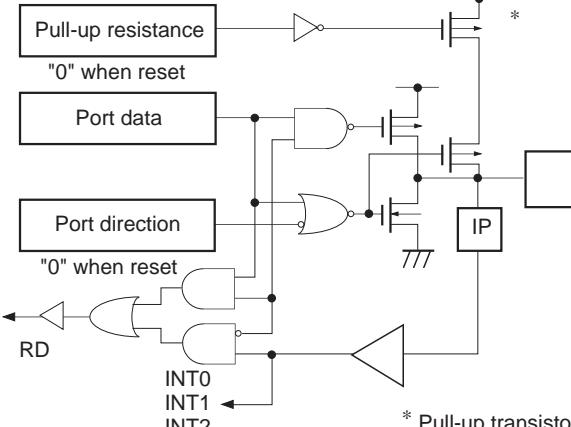
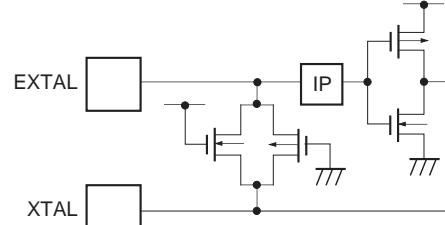
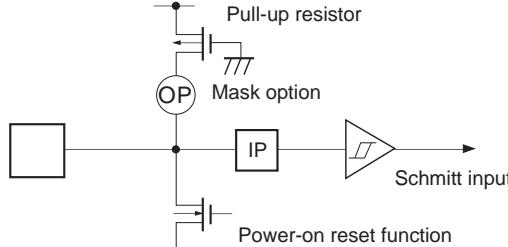
Symbol	I/O	Description	
PG0 to PG2	I/O	(Port G) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (3 pins)	
PI0/INT0 to PI3/INT3	I/O/Input	(Port I) 7-bit I/O ports. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits.	External interruption request inputs.
PI4 to PI6	I/O	(7 pins)	
EXTAL	Input	Crystal connectors for system clock oscillation. When the clock is supplied externally, input to EXTAL; opposite phase clock should be input to XTAL.	
XTAL	Output		
RST	I/O	Low-level active, system reset.	
AVREF	Input	Reference voltage input for A/D converter.	
AVss		A/D converter GND.	
VDD		Positive power supply.	
Vpp		Positive power supply for incorporated PROM writing. Connect to VDD during normal operation.	
Vss		GND	

Input/Output Circuit Formats for Pins

Pin	Circuit format	When reset
PA0/AN0 to PA7/AN7 8 pins	<p>Port A</p> <p>Pull-up resistance "0" when reset</p> <p>Port A data</p> <p>Port A direction "0" when reset</p> <p>Data bus ← RD (Port A)</p> <p>Port A input selection "0" when reset</p> <p>Input multiplexer</p> <p>A/D converter</p> <p>IP Input protection circuit</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB0/CINT PB1/CS0 PB3/SI0 PB6/SI1 4 pins	<p>Port B</p> <p>Pull-up resistance "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus ← RD (Port B)</p> <p>CINT CS0 SI0 SI1</p> <p>Schmitt input</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB2/SCK0 PB5/SCK1 2 pins	<p>Port B</p> <p>Pull-up resistance "0" when reset</p> <p>SCK OUT</p> <p>Output enable</p> <p>Port B output selection "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus ← RD (Port B)</p> <p>SCK in</p> <p>Schmitt input</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z

Pin	Circuit format	When reset
PB4/SO0 1 pin	<p>Port B</p> <p>Pull-up resistance</p> <p>SO</p> <p>Output enable</p> <p>Port B output selection "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus</p> <p>RD (Port B)</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB7/SO1 1 pin	<p>Port B</p> <p>Internal reset signal</p> <p>SO</p> <p>Output enable</p> <p>Port B output selection "1" when reset</p> <p>Port B data</p> <p>Data bus</p> <p>RD (Port B)</p> <p>* Pull-up transistors approx. 200kΩ</p>	High level
PC0 to PC7 8 pins	<p>Port C</p> <p>Pull-up resistance "0" when reset</p> <p>Port C data</p> <p>Port C direction "0" when reset</p> <p>Data bus</p> <p>RD (Port C)</p> <p>*1 High current drive of 12mA possible</p> <p>*2 Pull-up transistors approx. 10kΩ</p>	Hi-Z
PE0/EC0 PE1/EC1 PE2/RMC PE3/NMI 4 pins	<p>Port E</p> <p>Schmitt input</p> <p>IP</p> <p>EC0 EC1 RMC/NMI</p> <p>Data bus</p> <p>RD (Port E)</p>	Hi-Z

Pin	Circuit format	When reset
PE4/PWM 1 pin	<p>Port E</p>  <p>PWM</p> <p>Port E output selection "0" when reset</p> <p>Port E data "1" when reset</p> <p>Data bus RD (Port E)</p>	High level
PE5/TO 1 pin	<p>Port E</p>  <p>Output enable</p> <p>TO</p> <p>Port E output selection "00" when reset</p> <p>Port E output selection "0" when reset</p> <p>Port E data "1" when reset</p> <p>Data bus RD (Port E)</p>	High level
PD0 to PD7 PF0 to PF7 PG0 to PG2 PI4 to PI6 22 pins	<p>Port D</p> <p>Port F</p> <p>Port G</p> <p>Port I</p>  <p>Pull-up resistance "0" when reset</p> <p>Port data</p> <p>Port direction "0" when reset</p> <p>Data bus RD</p> <p>* Pull-up transistors approx. 10kΩ</p> <p>IP</p>	Hi-Z

Pin	Circuit format	When reset
PIO/INT0 to PI3/INT3 4 pins	 <p>Port I</p> <p>Pull-up resistance "0" when reset</p> <p>Port data</p> <p>Port direction "0" when reset</p> <p>Data bus RD</p> <p>INT0 INT1 INT2 INT3</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
EXTAL XTAL 2 pins	 <ul style="list-style-type: none"> Diagram shows circuit composition during oscillation. Feedback resistor is removed during stop. 	Oscillation
<u>RST</u> 1 pin	 <p>Pull-up resistor</p> <p>OP Mask option</p> <p>IP</p> <p>Schmitt input</p> <p>Power-on reset function (mask option)</p>	Low level

Absolute Maximum Ratings(V_{ss} = 0V reference)

Item	Symbol	Ratings	Unit	Remarks
Supply voltage	V _{DD}	–0.3 to +7.0	V	
	V _{pp}	–0.3 to +13.0	V	Incorporated PROM
	A _{Vss}	–0.3 to +0.3	V	
Input voltage	V _{IN}	–0.3 to +7.0 ^{*1}	V	
Output voltage	V _{OUT}	–0.3 to +7.0 ^{*1}	V	
High level output current	I _{OH}	–5	mA	Output per pin
High level total output current	ΣI _{OH}	–50	mA	Total for all output pins
Low level output current	I _{OL}	15	mA	Value per pin, excluding large current outputs
	I _{OLC}	20	mA	Value per pin ^{*2} for large current outputs
Low level total output current	ΣI _{OL}	100	mA	Total for all output pins
Operating temperature	T _{opr}	–10 to +75	°C	
Storage temperature	T _{stg}	–55 to +150	°C	
Allowable power dissipation	P _D	1000	mW	

^{*1} V_{IN} and V_{OUT} must not exceed V_{DD} + 0.3V.^{*2} The high current drive transistor is the N-ch transistor of Port C (PC).

Note) Usage exceeding absolute maximum ratings may permanently impair the LSI. Normal operation should be conducted under the recommended operating conditions. Exceeding these conditions may adversely affect the reliability of the LSI.

Recommended Operating Conditions(V_{SS} = 0V reference)

Item	Symbol	Min.	Max.	Unit	Remarks
Supply voltage	V _{DD}	4.5	5.5	V	High-speed mode guaranteed operation range ^{*1}
		3.5	5.5		Low-speed mode guaranteed operation range ^{*1}
		2.5	5.5		Guaranteed data hold range during stop
	V _{PP}	V _{PP} = V _{DD}		V	^{*5}
High level input voltage	V _{IH}	0.7V _{DD}	V _{DD}	V	^{*2}
	V _{IHS}	0.8V _{DD}	V _{DD}	V	Hysteresis input ^{*3}
	V _{IHEX}	V _{DD} - 0.4	V _{DD} + 0.3	V	EXTAL ^{*4}
Low level input voltage	V _{IL}	0	0.3V _{DD}	V	^{*2}
	V _{ILS}	0	0.2V _{DD}	V	Hysteresis input ^{*3}
	V _{ILEX}	-0.3	0.4	V	EXTAL ^{*4}
Operating temperature	T _{OPR}	-10	+75	°C	

^{*1} High-speed mode is 1/2 frequency demultiplication clock selection; low-speed mode is 1/16 frequency demultiplication clock selection.

^{*2} Value for each pin of normal input ports (PA, PB3, PB4, PB6, PC, PD, PF, PG, PI4 to PI6).

^{*3} Value of the following pins: RST, CINT, CS0, SCK0, SCK1, EC0, EC1, RMC, NMI, INT0, INT1, INT2, INT3.

^{*4} Specifies only during external clock input.

^{*5} V_{PP} and V_{DD} should be set to the same voltage.

Electrical Characteristics**DC Characteristics**

(Ta = -10 to +75°C, Vss = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
High level output voltage	VOH	PA to PD, PE4, PE5, PF, PG, PI	VDD = 4.5V, IOH = -0.5mA	4.0			V
			VDD = 4.5V, IOH = -1.2mA	3.5			V
Low level output voltage	VOL	PC	VDD = 4.5V, IOL = 1.8mA			0.4	V
			VDD = 4.5V, IOL = 3.6mA			0.6	V
Input current	I _H E	EXTAL	VDD = 5.5V, VIH = 5.5V	0.5		40	μA
	I _L E		VDD = 5.5V, VIL = 0.4V	-0.5		-40	μA
	I _H R	RST	VDD = 5.5V, VIL = 0.4V	-1.5		-400	μA
	I _L R	PA to PD*1, PF, PG, PI*1				-2.0	mA
	I _L	VDD = 4.5V, VIL = 4.0V	-10			μA	
I/O leakage current	I _I Z	PE0 to PE3	VDD = 5.5V, VI = 0, 5.5V			±10	μA
Power supply current*2	I _{DD} 1	VDD	High-speed mode operation (1/2 frequency demultiplier clock) VDD = 5.5V, 10MHz crystal oscillation (C ₁ = C ₂ = 15pF)		18	40	mA
	I _{DDS} 1		Sleep mode VDD = 5.5V, 10MHz crystal oscillation (C ₁ = C ₂ = 15pF)		1.1	8	mA
	I _{DDS} 3		Stop mode VDD = 5.5V, termination of 10MHz crystal oscillation .			30	μA
Input capacity	C _{IN}	Pins other than PB7, PE4, PE5, AVREF, VDD, Vss	Clock 1MHz 0V for no-measured pins		10	20	pF

*1 Pins PA to PD, and PF, PG, PI specify the input current when pull-up resistance has been selected;
leakage current when no resistance has been selected. (Excludes output PB7)

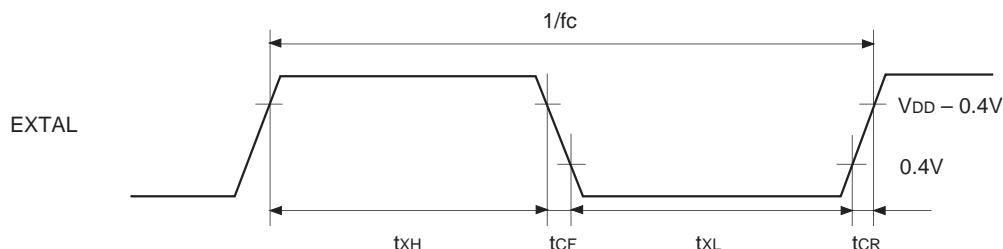
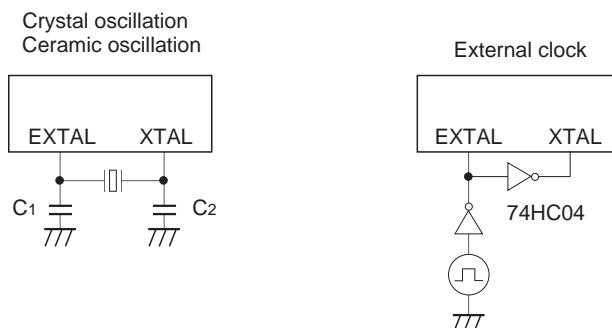
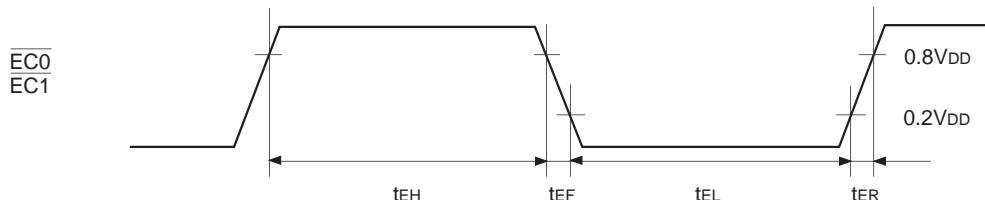
*2 When all pins are open.

AC Characteristics**(1) Clock timing**(Ta = -10 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V reference)

Item	Symbol	Pin	Conditions	Min.	Typ.	Max.	Unit
System clock frequency	f _C	XTAL EXTAL	Fig. 1, Fig. 2	1		10	MHz
System clock input pulse width	t _{XL} , t _{XH}	EXTAL	Fig. 1, Fig. 2 External clock drive	37.5			ns
System clock input rise time, fall time	t _{CR} , t _{CF}	EXTAL	Fig. 1, Fig. 2 External clock drive			200	ns
Event count input clock pulse width	t _{EH} , t _{EL}	$\overline{\text{EC}0}$ $\overline{\text{EC}1}$	Fig. 3	t _{sys} + 50*1			ns
Event count input clock rise time, fall time	t _{ER} , t _{EF}	$\overline{\text{EC}0}$ $\overline{\text{EC}1}$	Fig. 3			20	ms

*1 t_{sys} indicates the three values below according to the upper two bits (CPU clock selection) of the clock control register (address: 00FEH).

t_{sys} [ns] = 2000/f_C (upper two bits = "00"), 4000/f_C (upper two bits = "01"), 16000/f_C (upper two bits = "11")

**Fig. 1. Clock timing****Fig. 2. Clock applied condition****Fig. 3. Event count clock timing**

(2) Serial transfer (CH0)

(Ta = -10 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V reference)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
CS0 ↓ → SCK0 delay time	t _{DCSK}	SCK0	Chip select transfer mode (SCK0 = output mode)		t _{sys} + 200	ns
CS0 ↑ → SCK0 float delay time	t _{DCSKF}	SCK0	Chip select transfer mode (SCK0 = output mode)		t _{sys} + 200	ns
CS0 ↓ → SO0 delay time	t _{DCSO}	SO0	Chip select transfer mode		t _{sys} + 200	ns
CS0 ↑ → SO0 float delay time	t _{DCSOF}	SO0	Chip select transfer mode		t _{sys} + 200	ns
CS0 High level width	t _{WHCS}	SCK0	Chip select transfer mode	t _{sys} + 200		ns
SCK0 cycle time	t _{KCY}	SCK0	Input mode	2t _{sys} + 200		ns
			Output mode	16000/fc		ns
SCK0 High and Low level widths	t _{KH} t _{KL}	SCK0	Input mode	t _{sys} + 100		ns
			Output mode	8000/fc - 50		ns
SI0 input setup time (for SCK0 ↑)	t _{SIK}	SI0	SCK0 input mode	100		ns
			SCK0 output mode	200		ns
SI0 input hold time (for SCK0 ↑)	t _{SKI}	SI0	SCK0 input mode	t _{sys} + 200		ns
			SCK0 output mode	100		ns
SCK0 ↓ → SO0 delay time	t _{KSO}	SO0	SCK0 input mode		t _{sys} + 200	ns
			SCK0 output mode		100	ns

Note 1) t_{sys} indicates the three values below according to the upper two bits (CPU clock selection) of the clock control register (address: 00FEH).

t_{sys} [ns] = 2000/fc (upper two bits = "00"), 4000/fc (upper two bits = "01"), 16000/fc (upper two bits = "11")

Note 2) The load condition for the SCK0 output mode, SO0 output delay time is 50pF + 1TTL.

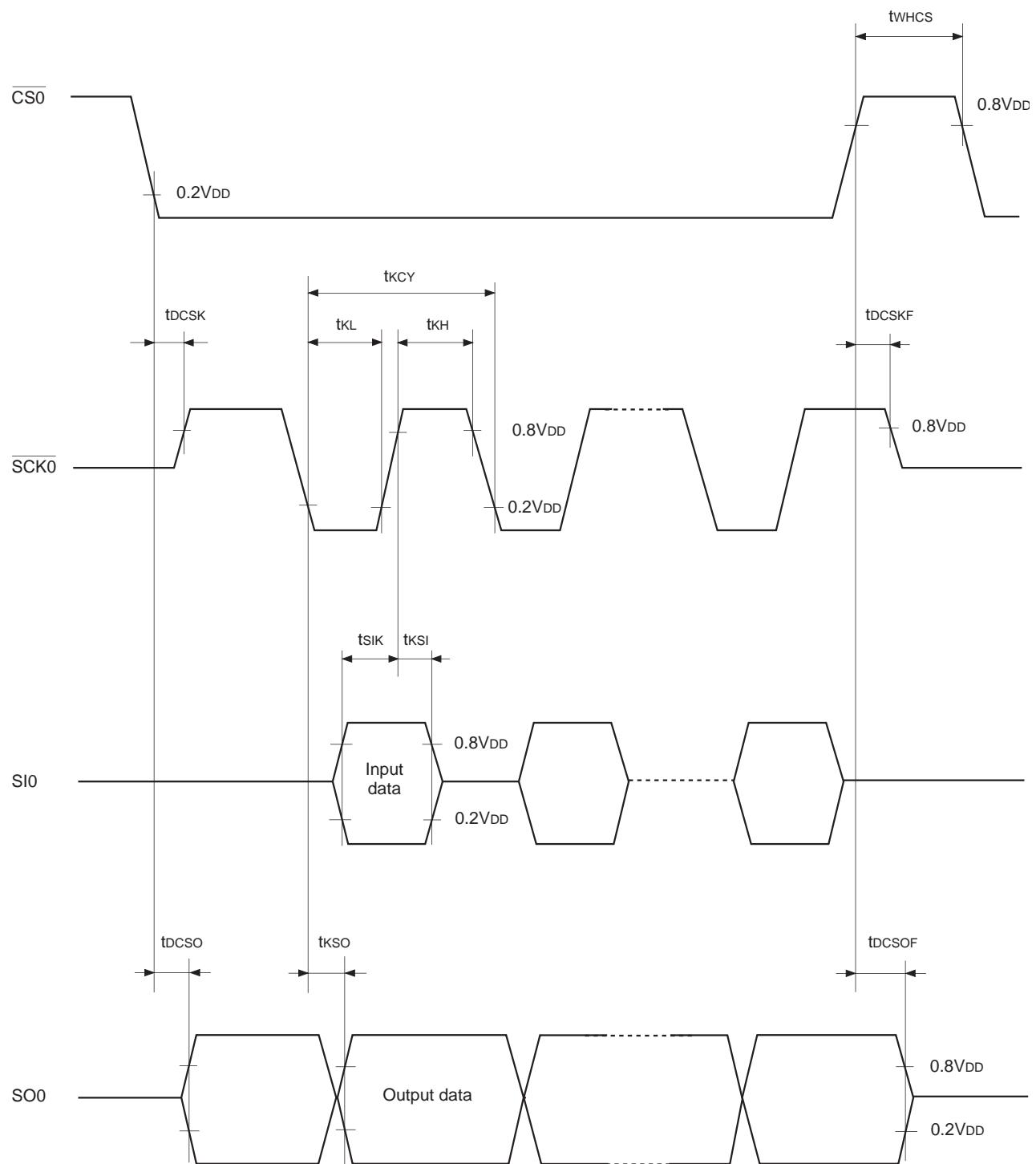
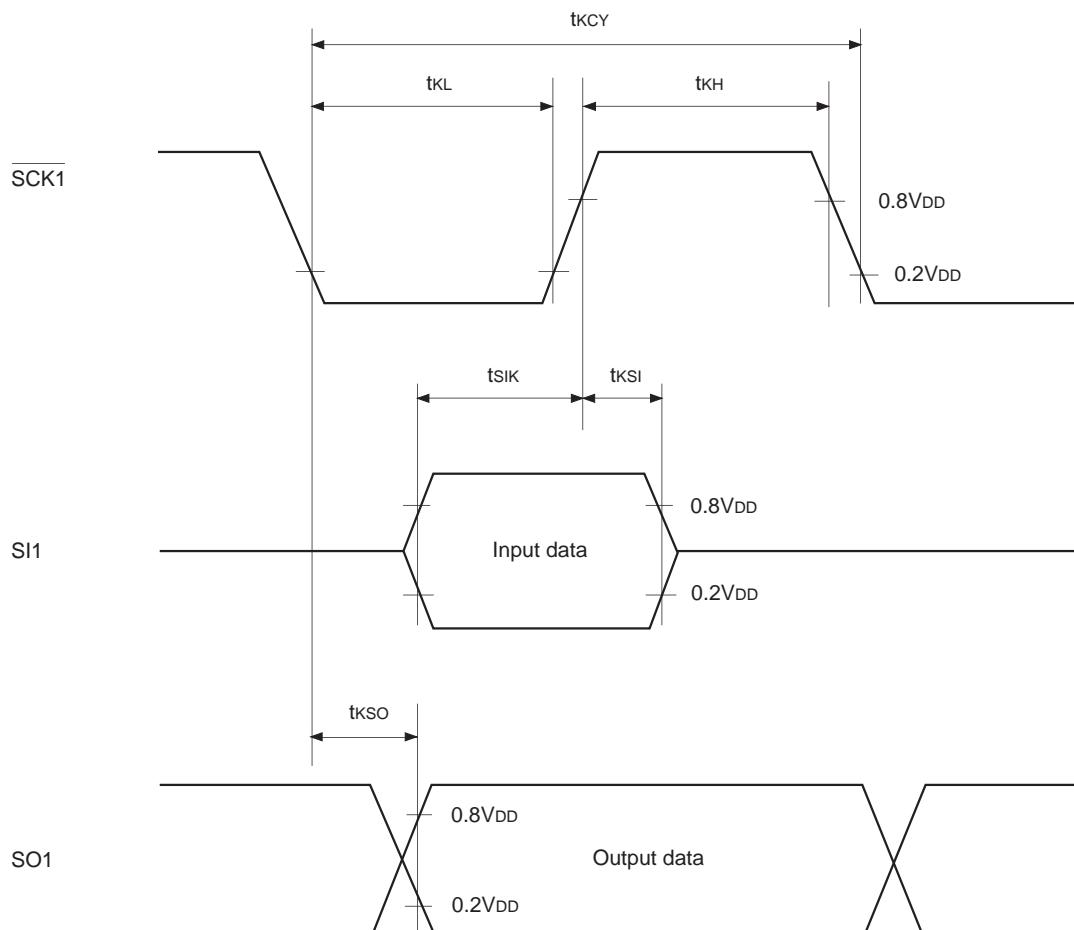


Fig. 4. Serial transfer CH0 timing

Serial transfer (CH1)

(Ta = -10 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V reference)

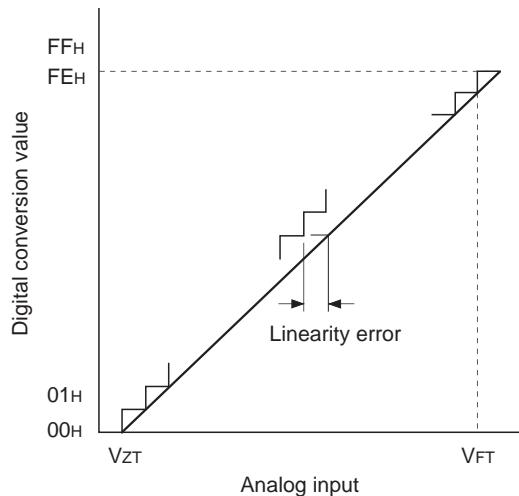
Item	Symbol	Pin	Condition	Min.	Max.	Unit
SCK1 cycle time	tkCY	SCK1	Input mode	1000		ns
			Output mode	16000/fc		ns
SCK1 High and Low level widths	tKH tKL	SCK1	Input mode	400		ns
			Output mode	8000/fc – 50		ns
SI1 input setup time (for SCK1 ↑)	tsIK	SI1	SCK1 input mode	100		ns
			SCK1 output mode	200		ns
SI1 input hold time (for SCK1 ↑)	tKSI	SI1	SCK1 input mode	200		ns
			SCK1 output mode	100		ns
SCK1 ↓ → SO1 delay time	tkSO	SO1	SCK1 input mode		200	ns
			SCK1 output mode		100	ns

Note) The load condition for the SCK1 output mode, SO1 output delay time is 50pF + 1TTL.**Fig. 5. Serial transfer CH1 timing**

(3) A/D converter characteristics

(Ta = -10 to +75°C, VDD = 4.5 to 5.5V, AVREF = 4.0 to AVDD, Vss = AVss = 0V reference)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error						± 3	LSB
Zero transition voltage	VZT ^{*1}		Ta = 25°C VDD = 5.0V VSS = AVSS = 0V	-10	70	150	mV
Full-scale transition voltage	VFT ^{*2}			4930	5050	5120	mV
Conversion time	tCONV			160/fADC ^{*3}			μs
Sampling time	tsAMP			12/fADC ^{*3}			μs
Reference input voltage	VREF	AVREF		VDD - 0.5		VDD	V
Analog input voltage	VIAN	AN0 to AN7		0		AVREF	V
AVREF current	IREF	AVREF	Operation mode		0.6	1.0	mA
	IREFS		Sleep mode Stop mode			10	μA



^{*1} VZT : Value at which the digital conversion value changes from 00H to 01H and vice versa.

^{*2} VFT : Value at which the digital conversion value changes from FEH to FFH and vice versa.

^{*3} fADC indicates the below values due to ADC operation clock selection.
During PS2 selection, fADC = fc/2
During PS1 selection, fADC = fc

Fig. 6. Definition of A/D converter terms

(4) Interruption, reset input (Ta = -10 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V reference)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
External interruption High and Low level widths	t _{IH} t _{IL}	INT0 INT1 INT2 INT3 NMI		1		μs
Reset input Low level width	t _{RS}	$\overline{\text{RST}}$		32/fc		μs

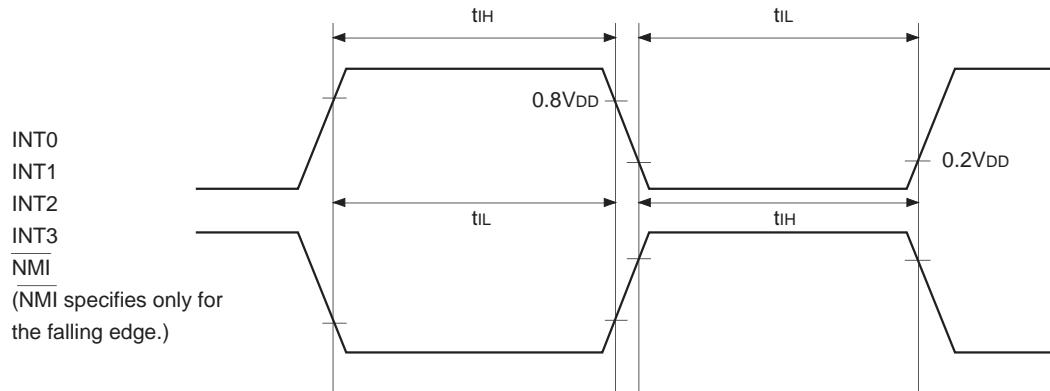
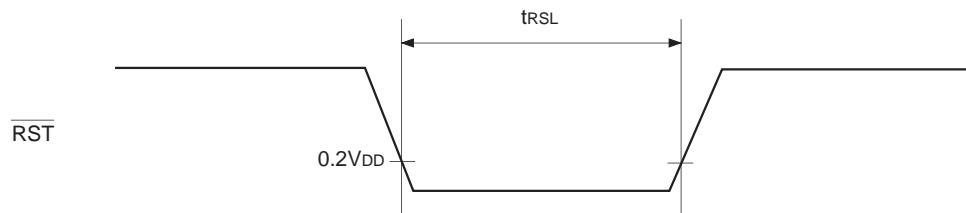


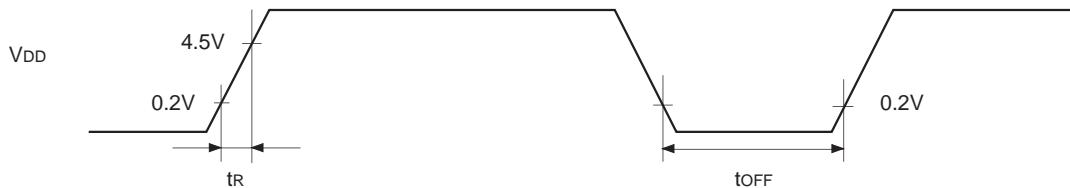
Fig. 7. Interruption input timing

Fig. 8. $\overline{\text{RST}}$ input timing

(5) Power-on reset

(Ta = -10 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V reference)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
Power supply rising time	t _R	V _{DD}	Power-on reset	0.05	50	ms
Power supply cut-off time	t _{OFF}		Repetitive power-on reset	1		ms



The power supply should rise smoothly.

Fig. 9. Power-on reset

Appendix

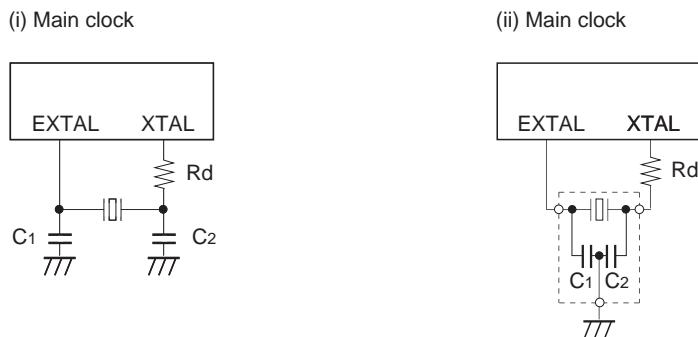


Fig. 10. SPC700 series recommended oscillation circuit

Manufacturer	Model	fc (MHz)	C1 (pF)	C2 (pF)	Rd (Ω)	Circuit example
MURATA MFG CO., LTD.	CSA4.19MG	4.19	30	30	0	(i)
	CSA8.00MTZ	8.00				
	CSA10.0MTZ	10.00				
	CST4.19MGW*	4.19				(ii)
	CST8.00MTW*	8.00				
	CST10.0MTW*	10.00				
RIVER ELETEC CORPORATION	HC-49/U03	4.19	12	12	0	(i)
		8.00				
		10.00				
KINSEKI LTD.	HC-49/U (-S)	4.19	27	27	0	
		8.00				
		10.00	20	20		

Those marked with an asterisk (*) signify types with built-in ground capacitance (C₁, C₂).

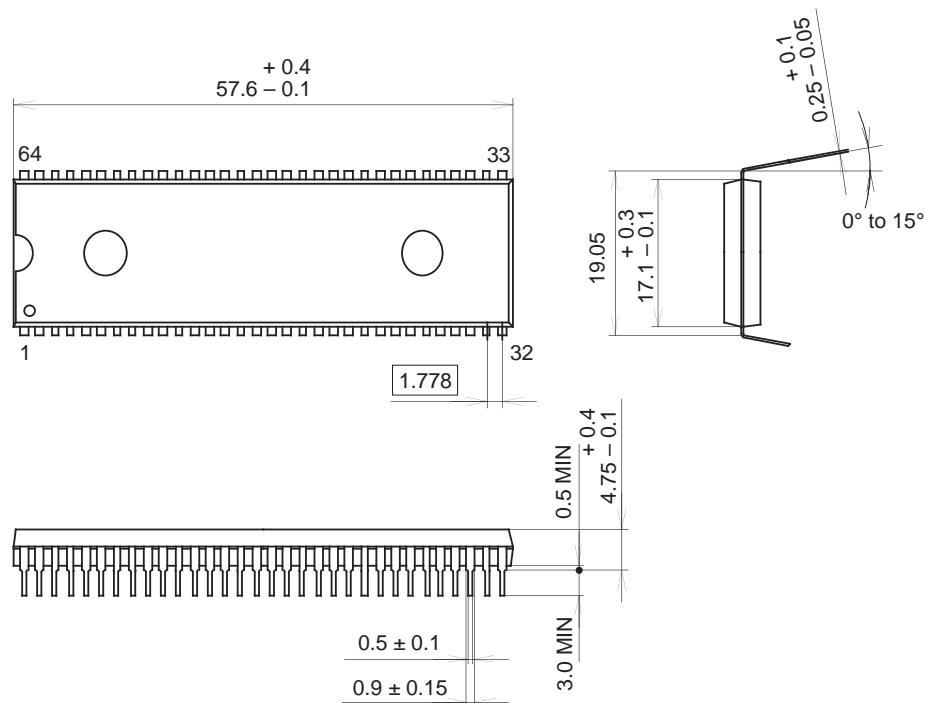
Product List

Optional item	Mask	CXP842P24Q-1-□□□
Package	64-pin plastic SDIP	64-pin plastic SDIP
ROM capacity	20K bytes/24K bytes	PROM 24K bytes
Reset pin pull-up resistor	Existent/non existent	Existent
Power-on reset circuit	Existent/non existent	Existent

Package Outline

Unit: mm

64PIN SDIP (PLASTIC)



PACKAGE STRUCTURE

SONY CODE	SDIP-64P-01
EIAJ CODE	SDIP064-P-0750
JEDEC CODE	_____

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE MASS	8.6g